

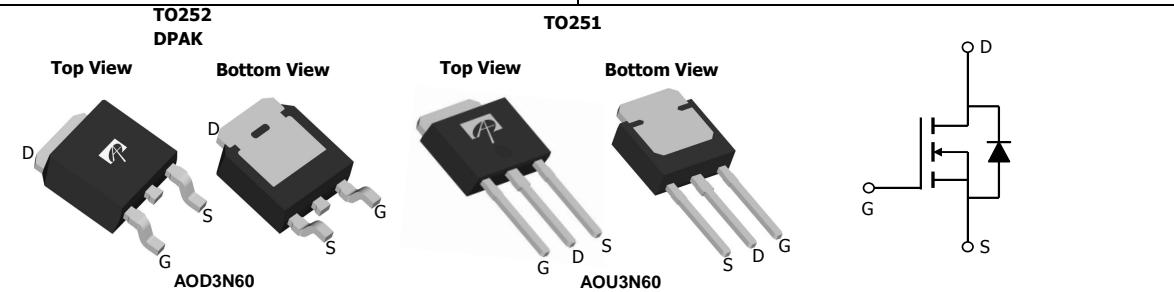
General Description

The AOD3N60 & AOU3N60 have been fabricated using an advanced high voltage MOSFET process that is designed to deliver high levels of performance and robustness in popular AC-DC applications. By providing low $R_{DS(on)}$, C_{iss} and C_{rss} along with guaranteed avalanche capability these parts can be adopted quickly into new and existing offline power supply designs.

Product Summary

V_{DS}	700V@150°C
I_D (at $V_{GS}=10V$)	2.5A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 3.5Ω

100% UIS Tested!
100% R_g Tested!



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ^B	I_D	2.5	A
$T_C=100^\circ C$		1.6	
Pulsed Drain Current ^C	I_{DM}	8	
Avalanche Current ^C	I_{AR}	2	A
Repetitive avalanche energy ^C	E_{AR}	60	mJ
Single pulsed avalanche energy ^H	E_{AS}	120	mJ
Peak diode recovery dv/dt	dv/dt	5	V/ns
Power Dissipation ^B	P_D	56.8	W
Derate above $25^\circ C$		0.45	W/°C
Junction and Storage Temperature Range	T_J, T_{STG}	-50 to 150	°C
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	T_L	300	°C

Thermal Characteristics

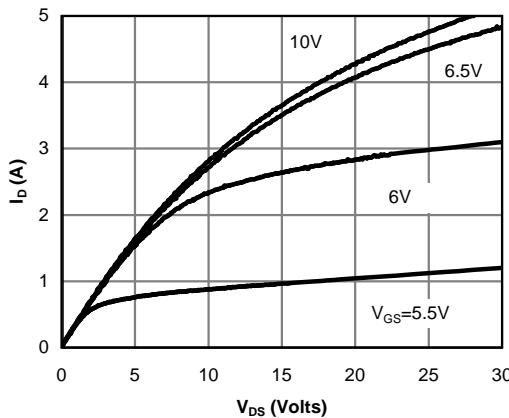
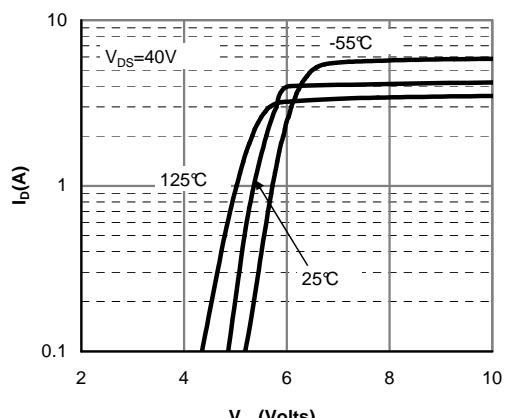
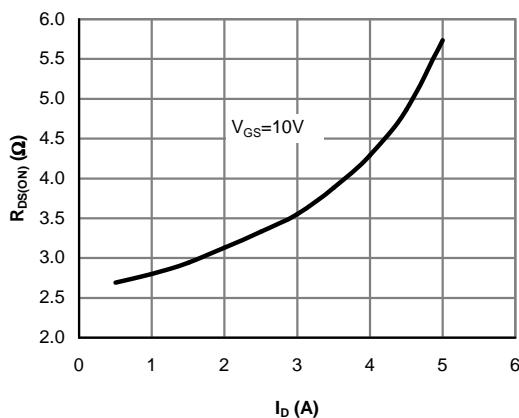
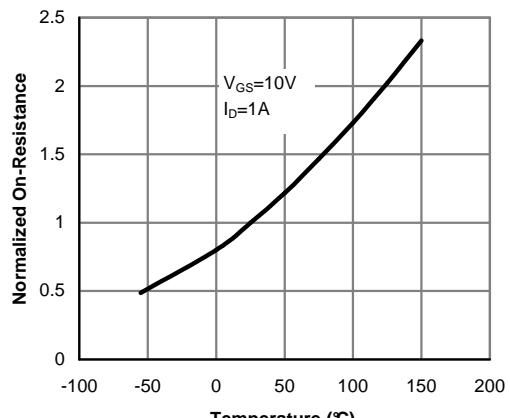
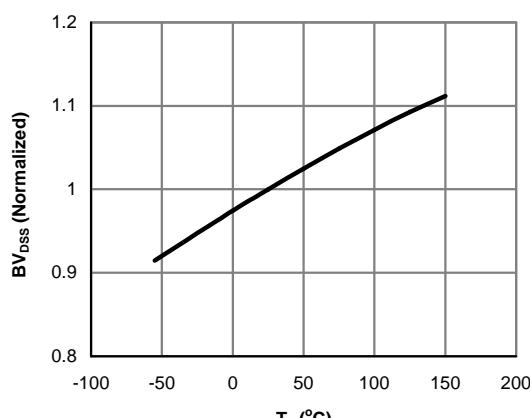
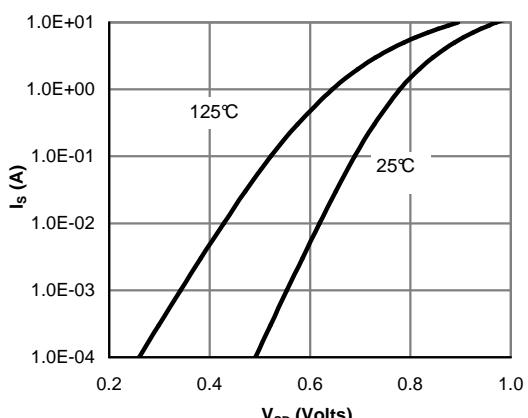
Parameter	Symbol	Typical	Maximum	Units
Maximum Junction-to-Ambient ^{A,G}	$R_{\theta JA}$	45	55	°C/W
Maximum Case-to-sink ^A	$R_{\theta CS}$	-	0.5	°C/W
Maximum Junction-to-Case ^{D,F}	$R_{\theta JC}$	1.8	2.2	°C/W

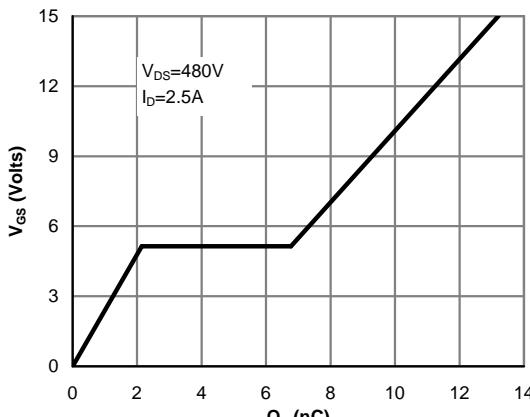
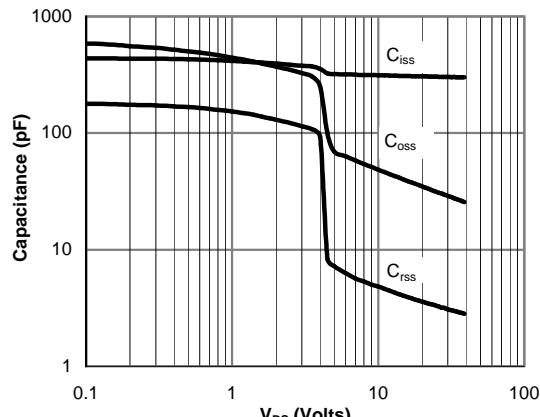
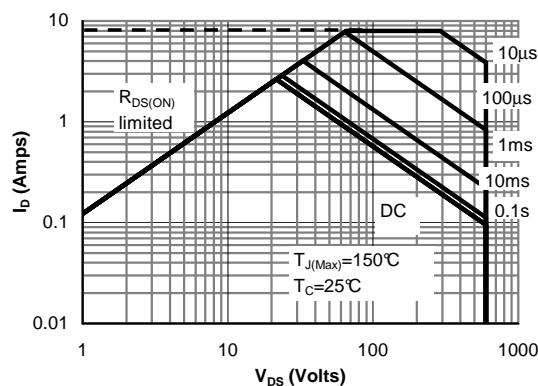
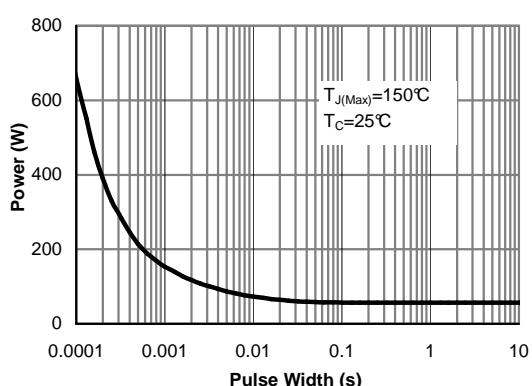
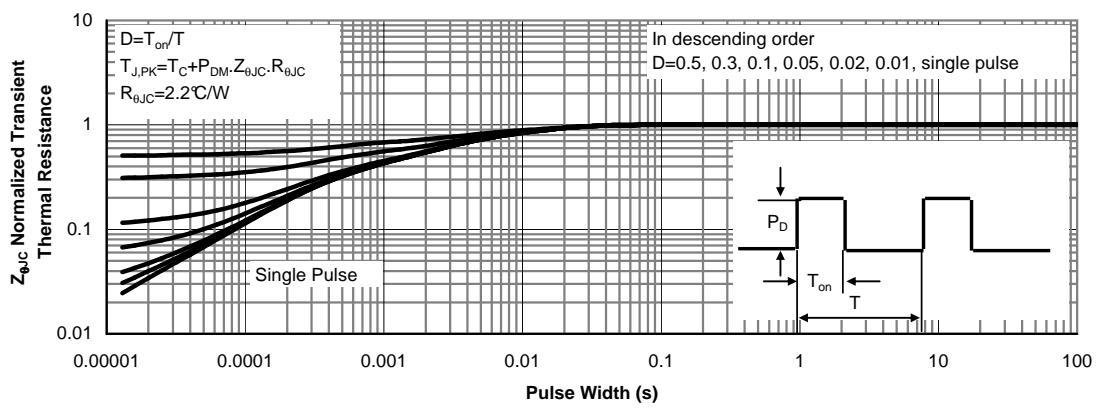
Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

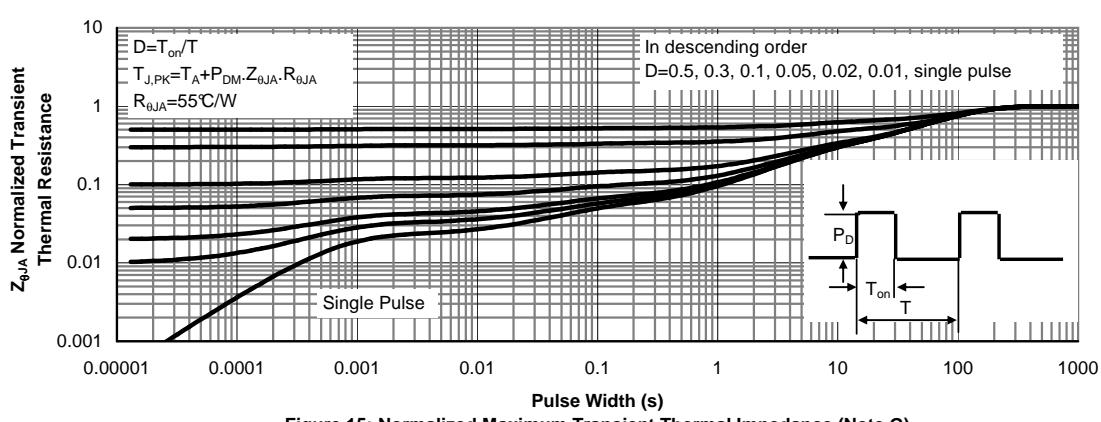
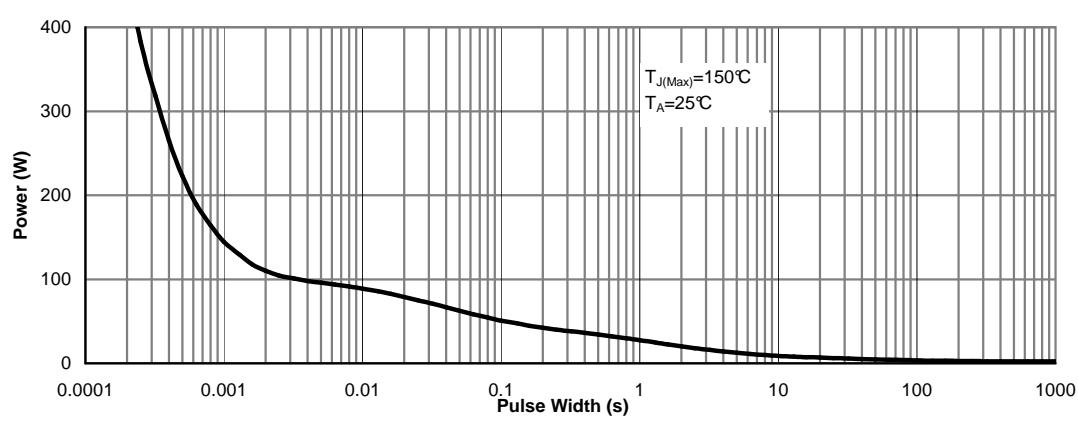
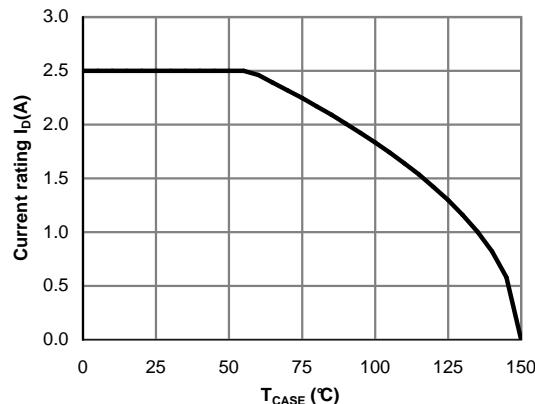
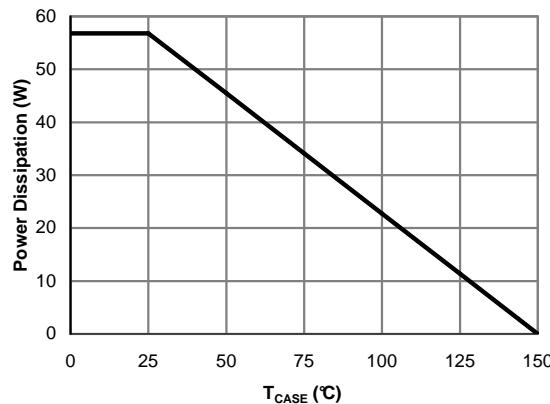
Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$	600			V
		$I_D=250\mu\text{A}, V_{GS}=0\text{V}, T_J=150^\circ\text{C}$		700		
$BV_{DSS}/\Delta T_J$	Zero Gate Voltage Drain Current	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$		0.65		$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=600\text{V}, V_{GS}=0\text{V}$		1		μA
		$V_{DS}=480\text{V}, T_J=125^\circ\text{C}$		10		
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 30\text{V}$			± 100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=5\text{V}, I_D=250\mu\text{A}$	3	4	4.5	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=1.25\text{A}$		2.9	3.5	Ω
g_{FS}	Forward Transconductance	$V_{DS}=40\text{V}, I_D=1.25\text{A}$		2.8		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.64	1	V
I_S	Maximum Body-Diode Continuous Current				2	A
I_{SM}	Maximum Body-Diode Pulsed Current				8	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1\text{MHz}$	240	304	370	pF
C_{oss}	Output Capacitance		25	31.4	38	pF
C_{rss}	Reverse Transfer Capacitance		2.6	3.3	4	pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	2.3	2.9	6	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=480\text{V}, I_D=2.5\text{A}$		9.9	12	nC
Q_{gs}	Gate Source Charge			2.1	3	nC
Q_{gd}	Gate Drain Charge			4.6	6	nC
$t_{D(\text{on})}$	Turn-On Delay Time	$V_{GS}=10\text{V}, V_{DS}=300\text{V}, I_D=2.5\text{A}, R_G=25\Omega$		17	20	ns
t_r	Turn-On Rise Time			17	20	ns
$t_{D(\text{off})}$	Turn-Off Delay Time			24	30	ns
t_f	Turn-Off Fall Time			16	20	ns
t_{rr}	Body Diode Reverse Recovery Time		$I_F=2.5\text{A}, dI/dt=100\text{A}/\mu\text{s}, V_{DS}=100\text{V}$	175	210	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=2.5\text{A}, dI/dt=100\text{A}/\mu\text{s}, V_{DS}=100\text{V}$		1.4	1.7	μC

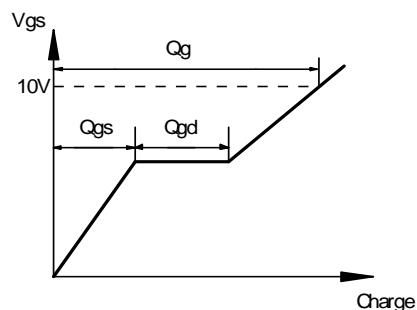
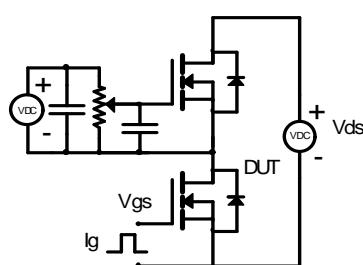
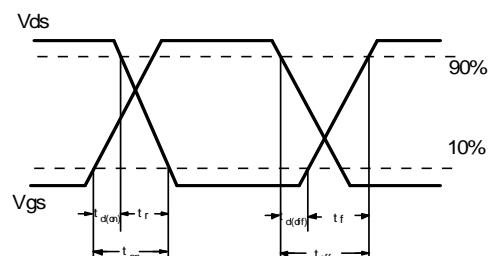
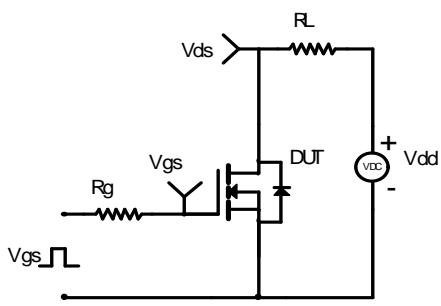
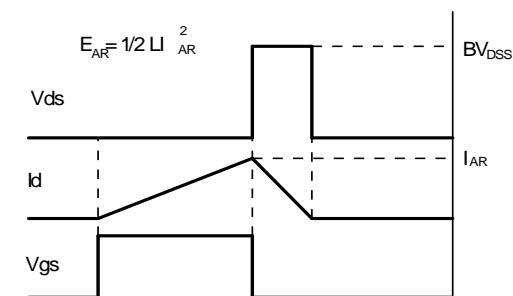
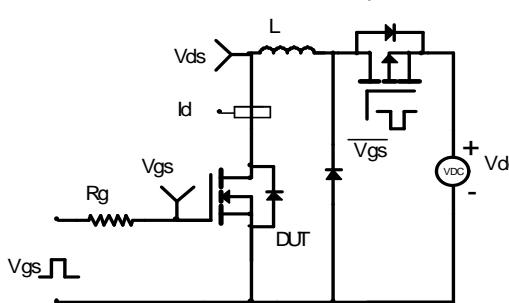
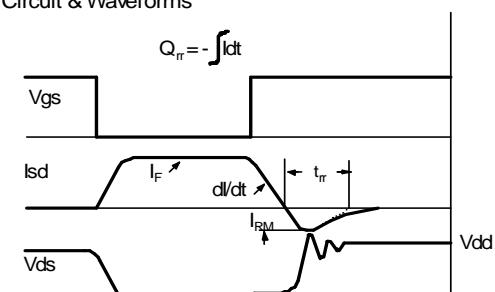
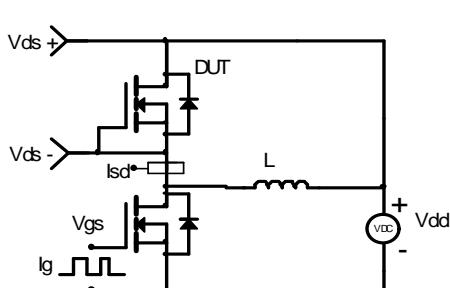
- A. The value of $R_{\theta JA}$ is measured with the device in a still air environment with $T_A=25^\circ\text{C}$.
B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$ in a TO252 package, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$.
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using $<300\ \mu\text{s}$ pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$.
G. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.
H. $L=60\text{mH}, I_{AS}=2\text{A}, V_{DD}=150\text{V}, R_G=10\Omega$, Starting $T_J=25^\circ\text{C}$

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature

Figure 5: Break Down vs. Junction Temperature

Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS


Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms


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